

698LF BOM-style material declaration. BI Technologies Corporation

9/16/2010

No content here is banned per E.U. R.o.H.S.. Average mass of 698LF thin film network is 1.0 grams each. Prepared by Eric Arnold (714) 447-2565
Weights above 1 milligram rounded to the nearest mg. Values less than 1 milligram given in scientific notation.

Sub-component	Material	% of total mass	Substance name	CAS #	Substance Weight (grams)	Special classification		
Die	substrate	0.97%	Al2O3	1344-28-1	0.010			
			CaO	1305-78-8	2.45E-06			
			FeO2	1345-25-1	4.90E-06			
			MgO	1309-48-4	2.45E-06			
			MnO2	1313-13-9	9.80E-06			
			SiO2, amorphous	7631-86-9	1.47E-05			
			TiO2	13463-67-7	4.90E-06			
			nichrome resistor	0.00003%	NiCrOx	combination of 7440-02-0, 7440-47-3, & 1308-38-9	3.51E-07	
			nickel barrier	0.0001%	Ni	7440-02-0	6.73E-07	
			gold conductor	0.001%	Au	7440-57-5	1.45E-05	
BCB passivation	0.001%	dvs-BCB, divinylsiloxane-bis-benzocyclobutene	124221-30-3	8.86E-06				
Leadframe	copper alloy	32.5%	Cu	7440-50-8	0.321			
			Fe	7439-89-6	0.008			
			P	7723-14-0	9.89E-05			
			Zn	7440-66-6	3.96E-04			
			Sn	7440-31-5	0.018			
			Ag	7440-22-4	0.002			
Die adhesive	conductive epoxy	0.1%	Ag	7440-22-4	0.001			
			trade secret	unknown	2.20E-04	non-hazardous		
Wire bonds	gold	0.01%	Au	7440-57-5	1.33E-04			
Molding compound	filled epoxy	64.5%	carbon black	1333-86-4	0.003			
			SiO2, fused silica	60676-86-0	0.523			
			trade secret	unknown	0.127	non-hazardous		
Ink marking	epoxy	0.01%	trade secret	unknown	1.00E-04	non-hazardous		